

C2220X683F1TACTU

Aliases (C2220X683F1TAC7800) SMD Comm X8G HT150C Flex, Ceramic, 0.068 uF, 1%, 100 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 2220, 3.5 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	130 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	2220
L	5.9mm +/-0.75mm
W	5mm +/-0.4mm
Т	1mm +/-0.15mm
S	3.5mm MIN
В	0.7mm +/-0.35mm

Packaging

Packaging Quantity

W	5mm +/-0.4mm	Toler
Т	1mm +/-0.15mm	Volta
S	3.5mm MIN	Diele
В	0.7mm +/-0.35mm	Temp
		Temp
Packaging Specifications		Capa

1000

T&R, 180mm, Plastic Tape

Specifications	
Capacitance	0.068 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	1%
Voltage DC	100 VDC
Dielectric Withstanding Voltage	250 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	14.7059 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitut	te - and
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